

**EXHIBIT A**

**PRELIMINARY DRAFT****LGA - QNL PACKAGE DEVELOPMENT**

<b><u>Project</u></b> LGA - QNL PACKAGE DEVELOPMENT	<b><u>NPEV</u></b>	<b><u>Resources</u></b>
<b><u>Description</u></b> Qualify new family of LGA-QNL laminate grid array packages for low to mid-lead count high performance applications. Identify product(s), design & procure substrate, qualify vendors, assemble on MCM-L overmold and saw line, test, conduct failure analysis, and report		
<b><u>Deliverables</u></b> Identify lead product and line up support to qualify the package Design and get substrates from qualified suppliers – assemble parts Perform qualification testing, conduct failure analysis and write final report	<b><u>Forecast</u></b> 10/98 12/98 4/99	<b><u>Actual</u></b>

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